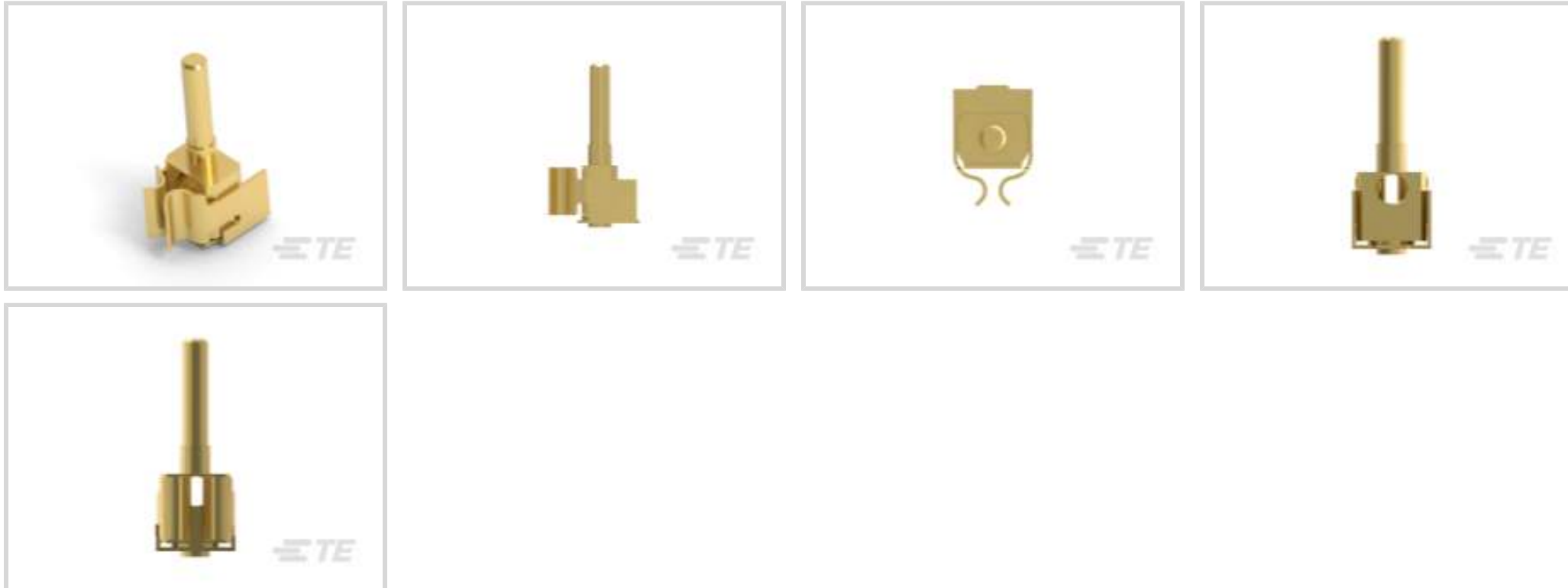




Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Connector Contacts



Contact Type: **Socket**

Contact Mating Area Plating Material: **Gold**

Contact Orientation: **Straight**

Connector & Contact Terminates To: **Printed Circuit Board**

Contact Current Rating (Max): **3 A**

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
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Contact Features

	30 µin
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Phosphor Bronze
Contact Type	Socket
Contact Mating Area Plating Material	Gold
Contact Orientation	Straight
Contact Current Rating (Max)	3 A

Termination Features

Termination Method to Printed Circuit Board	Through Hole - Solder
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Mechanical Attachment

Wire Insulation Support	Without
PCB Mount Retention	Without

Usage Conditions

Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
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Operation/Application

Circuit Application	Signal
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Packaging Features

Packaging Quantity	25
Packaging Method	Package

Product Compliance

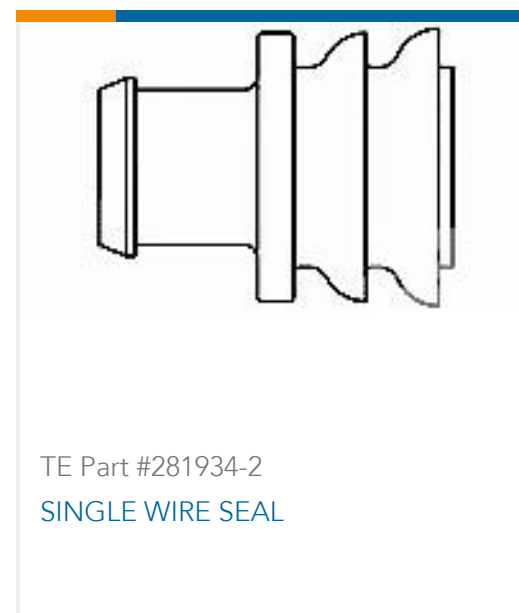
[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant with Exemptions
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUL 2021 (219) SVHC > Threshold: Pb (3.7% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



Documents

Product Drawings

HDI POWER CONTACT ASSY

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_532924-1_P.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_532924-1_P.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_532924-1_P.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English

Instruction Sheets

Instruction Sheet (U.S.)

Japanese

Instruction Sheet (U.S.)

English



AMP-HDI CONNECTOR JACKSCREW HARDWARE KITS, GUIDE PINS, AND GUIDE PIN

English